



Material Content Data Sheet



Sales Product Name				BSC093N04LS G		Issued		1. August 2018	
MA#				MA001299996					
Package				PG-TDSON-8-14		Weight*		118.64 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.804	0.68	0.68	6776	6776	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82		
	non noble metal	zinc	7440-66-6	0.039	0.03		328		
	non noble metal	iron	7439-89-6	0.778	0.66		6558		
wire	non noble metal	copper	7440-50-8	31.590	26.63	27.33	266274	273242	
	non noble metal	copper	7440-50-8	0.066	0.06	0.06	557	557	
	encapsulation	organic material	carbon black	1333-86-4	0.241	0.20		2032	
	plastics	epoxy resin	-	7.475	6.30		63007		
	inorganic material	silicondioxide	60676-86-0	40.510	34.16	40.66	341459	406498	
leadfinish	non noble metal	tin	7440-31-5	1.243	1.05	1.05	10474	10474	
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	315	315	
solder	non noble metal	tin	7440-31-5	0.022	0.02		187		
	noble metal	silver	7440-22-4	0.028	0.02		234		
	non noble metal	lead	7439-92-1	1.060	0.89	0.93	8936	9357	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	zinc	7440-66-6	0.021	0.02		180		
	non noble metal	iron	7439-89-6	0.428	0.36		3604		
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.63	15.01	146328	150157	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
	non noble metal	iron	7439-89-6	0.017	0.01		143		
	non noble metal	copper	7440-50-8	16.898	14.24	14.25	142438	142624	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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